

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Paul Robert Hoffman and David Albert Zoba
Assignee: Amkor Technology, Inc.
Title: Structures For Improving Heat Dissipation In
Stacked Semiconductor Packages
Serial No.: Not Yet Assigned File Date: Herewith
Examiner: Not Yet Assigned Art Unit: Not Yet Assigned
Docket No.: AMK-11317-1D

Date: February 2, 2004

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

PRELIMINARY AMENDMENT

Dear Sir:

Prior to assessing the filing fee, and prior to examining
the application, please amend the application as follows.